

**Page 17, please replace the paragraph spanning line 18 through page 18, line 4, with the following rewritten paragraph:**

B6  
As described in detail above, in accordance with the present invention, fine processing of copper, silver, gold, or an alloy containing as a main component at least one of these metals, become possible by means of reactive-ion etching method. In addition to this, in accordance with the invention, there is provided a mask having excellent stability and free from corrosion by the plasma of the etching gases wherein the etching gases contain at least nitrogen oxide and are usable for copper, silver, gold, or an alloy containing as a main component at least one of these metals.

**In the Claims:**

**Kindly amend claim 5 as follows:**

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5. (Amended) A dry etching method comprising etching a metallic surface of copper, silver, gold, or an alloy containing as a main component at least one of these metals by plasma of an etching gas containing nitrogen oxide and hydrogen, or nitrogen oxide and a hydrogen-containing compound while being reacted with the plasma.

**In the Abstract:**

**Kindly rewrite the abstract as per the attached separate sheet.**